

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
PEI-CHENG HSU	07/10/2017
HSIN-CHANG LEE	07/10/2017
YUN-YUE LIN	07/10/2017
HSUAN-CHEN CHEN	07/10/2017
HSUAN-I WANG	07/10/2017
ANTHONY YEN	12/20/2017
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	8, LI-HSIN RD. 6
Internal Address:	HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15380121
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	214-651-5000
Email:	ipdocketing@haynesboone.com
Correspondent Name:	HAYNES AND BOONE, LLP IP SECTION
Address Line 1:	2323 VICTORY AVENUE
Address Line 2:	SUITE 700
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	20160673/24061.3431US01
NAME OF SUBMITTER:	LINDA INGRAM
SIGNATURE:	/Linda Ingram/
DATE SIGNED:	03/01/2018

PATENT

Total Attachments: 5

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ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|------------------------|----|---------------------------------|
| (1) | Pei-Cheng HSU | of | Taipei, Taiwan (R.O.C.) |
| (2) | Hsin-Chang LEE | of | Hsinchu County, Taiwan (R.O.C.) |
| (3) | Yun-Yue LIN | of | Hsinchu City, Taiwan (R.O.C.) |
| (4) | Hsuan-Chen CHEN | of | Hsinchu, Taiwan (R.O.C.) |
| (5) | Hsuan-I WANG | of | Hsinchu, Taiwan (R.O.C.) |
| (6) | Anthony YEN | of | Hsinchu, Taiwan (R.O.C.) |

have invented certain improvements in

PELLICLE STRUCTURES AND METHODS OF FABRICATING THEREOF

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and

 X filed on **December 15, 2016** and assigned application number **15/380,121** and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, **Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC")**, No. 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

Docket No.: 20160673/24061.3431US01
Customer No.: 000042717

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: **Pei-Cheng HSU**

Residence Address: No. 23, Alley 12, Lane 63, Wu-Cheng Street, Taipei, Taiwan (R.O.C.)

Dated: 2017.7.10

Pei-Cheng Hsu
Inventor Signature

Inventor Name: **Hsin-Chang LEE**

Residence Address: 3F., No.26, Ln. 394, Xianzheng 2nd Rd., Zhubei City, Hsinchu County 302, Taiwan (R.O.C.)

Dated: 2017.7.10

Hsin-Chang Lee
Inventor Signature

Inventor Name: **Yun-Yue LIN**

Residence Address: No.388, Jinshui St, Xiangshan Dist, Hsinchu City 300, Taiwan (R.O.C.)

Dated: 2017.7.10

Yun Yue Lin
Inventor Signature

Docket No.: 20160673/24061.3431US01
Customer No.: 000042717

Inventor Name: **Hsuan-Chen CHEN**

Residence Address: No. 8, Li-Hsin Rd., No. 6, Hsinchu Science Park, Hsinchu 300-78 (R.O.C.)

Dated: 2017 / 7 / 10


Inventor Signature

Inventor Name: **Hsuan-I WANG**

Residence Address: No. 8, Li-Hsin Rd., No. 6, Hsinchu Science Park, Hsinchu 300-78 (R.O.C.)

Dated: 2017 / 7 / 10

Hsuan-I Wang
Inventor Signature

Inventor Name: **Anthony YEN**

Residence Address: 20F-9, 188 Guanxin Road, Hsinchu 300, Taiwan (R.O.C.)

Dated: _____

Inventor Signature

ASSIGNMENT

WHEREAS, we,

- | | | | |
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NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

Inventor Name: **Hsuan-Chen CHEN**

Residence Address: **No. 8, Li-Hsin Rd., No. 6, Hsinchu Science Park, Hsinchu 300-78 (R.O.C.)**

Dated: _____

Inventor Signature

Inventor Name: **Hsuan-I WANG**

Residence Address: **No. 8, Li-Hsin Rd., No. 6, Hsinchu Science Park, Hsinchu 300-78 (R.O.C.)**

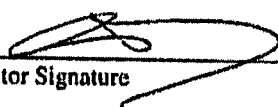
Dated: _____

Inventor Signature

Inventor Name: **Anthony YEN**

Residence Address: **20F-9, 188 Guanxin Road, Hsinchu 300, Taiwan (R.O.C.)**

Dated: 12/20/2017



Inventor Signature